

REMARKS/ARGUMENTS

Applicants would like to thank the Examiner for the careful consideration given the present application. The application has been carefully reviewed in light of the Office Action, and amended as necessary to more clearly and particularly describe the subject matter which applicants regard as the invention.

Regarding the rejection of claims 13 and 23-25 under the second paragraph of 35 U.S.C. §112, applicants have amended claim 13 to properly recite a closed set of items as required of Markush groups. Further, applicants have amended claim 23 to provide each limitation therein with sufficient antecedent basis in compliance with the second paragraph of §112.

Applicants note, with appreciation, the identification of claims 8-11 as being allowable if rewritten in independent form including all of the limitation of the base claim and any intervening claims. Applicants have adopted the Examiner's suggestion pertaining to claim 8 by incorporating the limitations of claim 8 into claim 1. Accordingly, applicants respectfully submit that claim 1, as amended, is allowable.

Similarly, applicants also note, with appreciation, the identification of claims 20-22 as being allowable if rewritten in independent form including all of the limitation of the base claim and any intervening claims. Just as before, applicants have adopted the Examiner's suggestion pertaining to claim 20 by incorporating the limitations of claim 20 into claim 12. Thus, applicants respectfully submit that claim 12, as amended, is allowable.

Claims 23-25 stand rejected under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 5,324,813 to Hougham et al. in view of U.S. Patent No. 6,080,640 to Gardner et al. Hougham et al. is cited in the Office action as teaching the step of heating an integrated circuit with an insulating polyimide layer disposed thereon to a temperature sufficient to evaporate an organic solvent in which the polyimide has been dispersed. However, Hougham et al. actually discloses heating a film, after being cast and dried, to a high temperature to initiate ring closure in the amide. Col. 4, Lines 17-20. Hougham et al. is silent on the temperature required to perform the ring closing, and fails to teach heating the integrated circuit and

Application No. 09/890,378  
Response Dated December 16, 2003  
Reply to Office Action of July 30, 2003

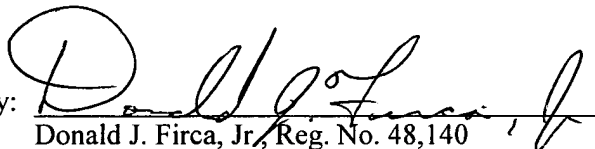
insulating polyimide layer disposed thereon to a temperature sufficient to evaporate the organic solvent, as claimed in claim 23.

Further with regard to the rejection of claims 23-25 as being unpatentable over Hougham et al. in view of Gardner et al., applicants respectfully submit that the references lack sufficient motivation therein to justify their combination. Gardner et al. is directed toward a "method of making a high density integrated circuit formed by low temperature fabrication of a first substrate structure having a transistor formation and metal interlevel lines thereon and a second substrate structure having a transistor formation and metal interlevel lines thereon." Col. 4, Lines 9-15. In contrast, the portion of the Hougham et al. disclosure discussed in the preceding paragraph, teaches heating of the film to initiate ring closure in the amide. Accordingly, since the teachings of Hougham et al. and Gardner et al. conflict, there would be no motivation to combine them. Thus, applicants respectfully submit that claims 23-25 are allowable.

In light of the foregoing, it is respectfully submitted that the present application is in a condition for allowance and notice to that effect is hereby requested. If it is determined that the application is not in a condition for allowance, the Examiner is invited to initiate a telephone interview with the undersigned attorney to expedite prosecution of the present application.

If there are any additional fees resulting from this communication, please charge same to our Deposit Account No., referencing our Docket No. UA.335.

Respectfully submitted,  
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Date: December 16, 2003

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